TX7-705C-C-ST3

STRATUM III SMD TCXO CMOS

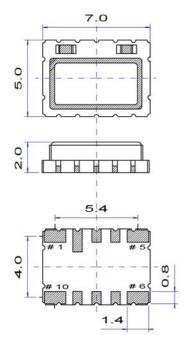


Features

- Applications: transmission, TDM networks, SDH, SONET, wireless communications, IEEE 1588v2, SyncE, STRATUM III, wireless backhaul, metro carrier Ethernet, femtocells, picocells
- Holdover stability: ±0.37 ppm over 24 h
- Overall stability: ±4.60 ppm including 20 years aging
- Output signal: CMOS
- Compatible to the DFA S2 (Fordahl SA)

Specification	
9.83040 ~ 32.0 MHz	
10.0, 12.80, 16.3840, 19.440, 20.0, 25.0, 26.0 & 32.0 MHz	
≤ ±4.60 ppm	overall stability including 20 years aging
≤ ±0.28 ppm	-40 ~ +85 °C
≤ ±3.0 ppm	20 years
≤ ±0.37 ppm	over 24 hours
≤ ±0.50 ppm	@ +25 °C
+3.3 V or +5.0 V	±5 %
< 6 mA	
CMOS	
15 pF	±5 %
-145 dBc/Hz	@ 10 kHz
0 ~ +70 °C	indoor use
-40 ~ +85 °C	outdoor use
-55 ~ +125 °C	
tape & reel tape only	500 or 1'000 pieces < 500 pieces
	9.83040 ~ 32.0 MHz 10.0, 12.80, 16.3840, ≤ ±4.60 ppm ≤ ±0.28 ppm ≤ ±0.37 ppm ≤ ±0.50 ppm +3.3 V or +5.0 V < 6 mA CMOS 15 pF -145 dBc/Hz 0 ~ +70 °C -40 ~ +85 °C -55 ~ +125 °C tape & reel

⁽¹⁾ Including: frequency stability, vs temperature, supply change of ±5 % and aging over 24 hours



Pin function

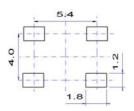
1 not connected

5 GND

6 Output

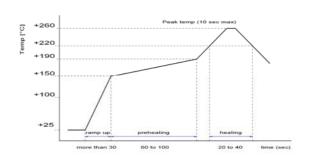
10 Vdc

Example for solder pattern



All other pins are not connected

Do not design any conductive path between the pattern Example for IR reflow soldering temperature



2002/95/EC RoHS compliant

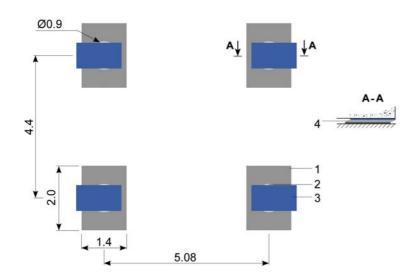
ISO 9001

TX7-705C-C-ST3

STRATUM III SMD TCXO **CMOS**



Accuracy of fit of the pinning of TX7-705-C (QuartzCom AG) on the footprint recommended for DFA S2 (Fordahl SA) in comparison with the DFA S2 pinning fit



- 1: DFA S2 footprint
- 2. DFA S2 pin
- 3. TX7-705-C pin
- 4. Solder

DFA S2 footprint with DFA S2 pin

